7SB3257

Mux / Demux Bus Switch

The 7SB3257 Mux / Demux Bus Switch is an advanced high−speed line switch in ultra−small footprint.

Features

- High Speed: t_{PD} = 0.25 ns (Max) @ V_{CC} = 4.5 V
- 3 Ω Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Ultra−Small Packages
- These are Pb−Free Devices

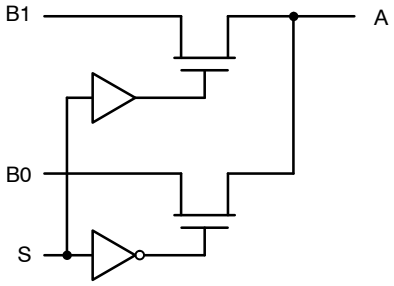


Figure 1. Logic Diagram

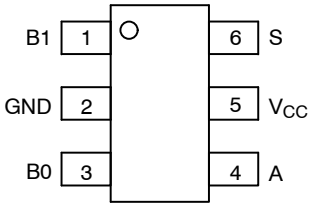


Figure 2. TSOP−6/SC−88 (Top View)

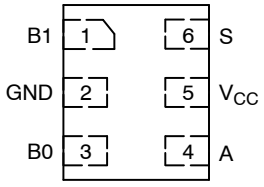


Figure 3. ULLGA6/UDFN6 (Top View)

Function Table

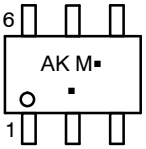
Input S	Function
L	A = B0
H	A = B1

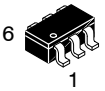
ON Semiconductor®

http://onsemi.com

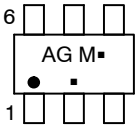
MARKING DIAGRAMS

SOT−363/SC70−6/SC−88
DF SUFFIX
CASE 419B

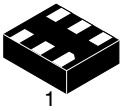




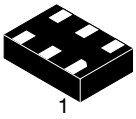
TSOP−6
DT SUFFIX
CASE 318G



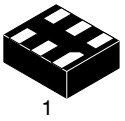
ULLGA6
1.0 x 1.0
CASE 613AD



ULLGA6
1.2 x 1.0
CASE 613AE



ULLGA6
1.45 x 1.0
CASE 613AF



UDFN6
1.2 x 1.0
CASE 517AA

AK, AG, K, D, L = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

Table 1. MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_{IN}	Control Pin Input Voltage		−0.5 to +7.0	V
$V_{I/O}$	Switch Input / Output Voltage		−0.5 to +7.0	V
I_{IK}	Control Pin DC Input Diode Current	V_{IN} < GND	−50	mA
I_{OK}	Switch I/O Port DC Diode Current	$V_{I/O}$ < GND	−50	mA
I_O	On−State Switch Current		±128	mA
	Continuous Current Through V_{CC} or GND		±150	mA
I_{CC}	DC Supply Current per Supply Pin		±150	mA
I_{GND}	DC Ground Current per Ground Pin		±150	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		150	°C
θ_{JA}	Thermal Resistance	SC−88 / TSOP−6 (Note 1) ULLGA6/UDFN6	333 496	°C/W
P_D	Power Dissipation in Still Air at 85°C	SC−88 / TSOP−6 (Note 1) ULLGA6/UDFN6	200 252	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Mode (Note 2) Machine Mode (Note 3) Charged Device Mode (Note 4)	>2000 >200 N/A	V
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 85°C (Note 5)		±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm−by−1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/ JESD22−A114−A
3. Tested to EIA/ JESD22−A115−A
4. Tested to JESD22−C101−A
5. Tested to EIA / JESD78.

Table 2. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Positive DC Supply Voltage		4.0	5.5	V
V_I	Control Pin Input Voltage		0	5.5	V
$V_{I/O}$	Switch Input / Output Voltage		0	5.5	V
T_A	Operating Free−Air Temperature		−55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	Control Input Switch I/O	0 0	5 DC	nS/V

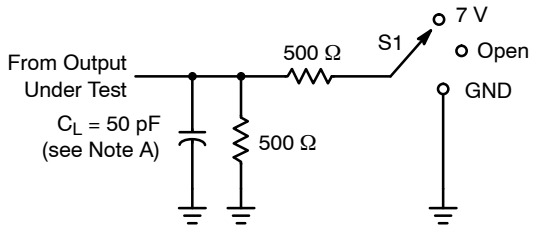
Table 3. DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = 25°C			T_A = −55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
V_{IK}	Clamp Diode Voltage	I_{IN} = −18 mA	4.5			−1.2		−1.2	V
V_{IH}	High−Level Input Voltage (Control)		4.0 to 5.5	2.0			2.0		V
V_{IL}	Low−Level Input Voltage (Control)		4.0 to 5.5			0.8		0.8	V
I_{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5$ V	5.5			±0.1		±1.0	μA
I_{OFF}	Power Off Leakage Current	$V_{I/O}$ = 0 to 5.5 V	0			±0.1		±1.0	μA
I_{CC}	Quiescent Supply Current	I_O = 0, V_{IN} = V_{CC} or 0 V	5.5			±0.1		±1.0	μA
ΔI_{CC}	Increase in Supply Current (Control Pin)	One input at 3.4 V; Other inputs at V_{CC} or GND	5.5					2.5	mA
R_{ON}	Switch ON Resistance	$V_{I/O}$ = 0, $I_{I/O}$ = 64 mA $I_{I/O}$ = 30 mA	4.5		3 3	7 7		7 7	Ω
		$V_{I/O}$ = 2.4, $I_{I/O}$ = 15 mA	4.5		6	15		15	
		$V_{I/O}$ = 2.4, $I_{I/O}$ = 15 mA	4.0		10	20		20	

Table 4. AC ELECTRICAL CHARACTERISTICS

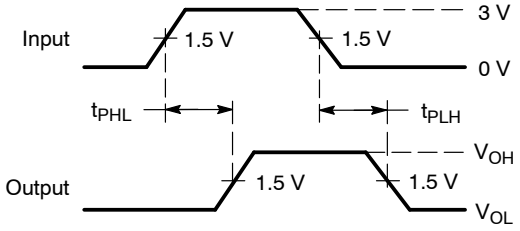
Symbol	Parameter	V_{CC} (V)	Test Condition	T_A = 25°C			T_A = −55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t_{PD}	Propagation Delay, A to B or B to A	4.0 to 5.5	See Figure 4			0.25		0.25	ns
t_{EN}	Output Enable Time	4.5 to 5.5		0.8	2.5	4.2	0.8	4.2	ns
		4.0		0.8	3.0	4.6	0.8	4.6	
t_{DIS}	Output Disable Time	4.5 to 5.5		0.8	3.1	4.8	0.8	4.8	ns
		4.0		0.8	2.9	4.4	0.8	4.4	
C_{IN}	Control Input Capacitance	5.0	V_{IN} = 3 V or 0		2.0				pF
$C_{IO(ON)}$	Switch On Capacitance	5.0	Switch ON		10				pF
$C_{IO(OFF)}$	Switch Off Capacitance	5.0	Switch OFF		3.5				pF

AC Loading and Waveforms

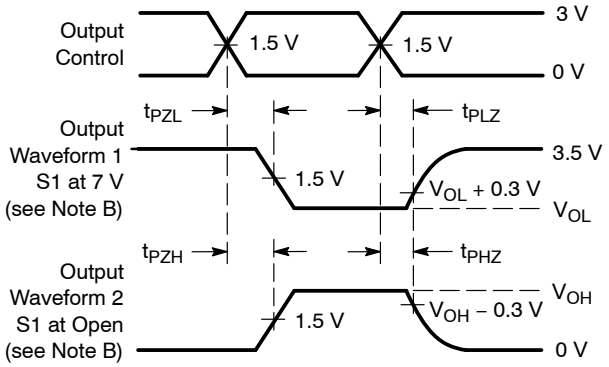


TEST	S1
t_{PD} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 7 V GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The output is measured with one input transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 4. Load Circuit and Voltage Waveforms

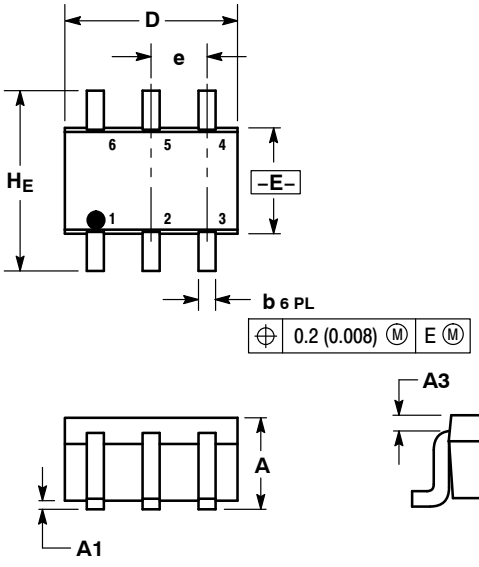
DEVICE ORDERING INFORMATION

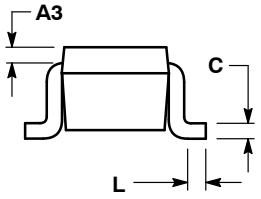
Device	Package	Shipping†
7SB3257DTT1G	TSOP−6 (Pb−Free)	3000 / Tape & Reel
7SB3257DFT2G	SC−88 (Pb−Free)	3000 / Tape & Reel
7SB3257AMX1TCG	ULLGA6 − 0.5 mm Pitch (Pb−Free)	3000 / Tape & Reel
7SB3257BMX1TCG	ULLGA6 − 0.4 mm Pitch (Pb−Free)	3000 / Tape & Reel
7SB3257CMX1TCG	ULLGA6 − 0.35 mm Pitch (Pb−Free)	3000 / Tape & Reel
7SB3257MUTCG	UDFN6 − 0.4 mm Pitch (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC−88/SC70−6/SOT−363
CASE 419B−02
ISSUE W

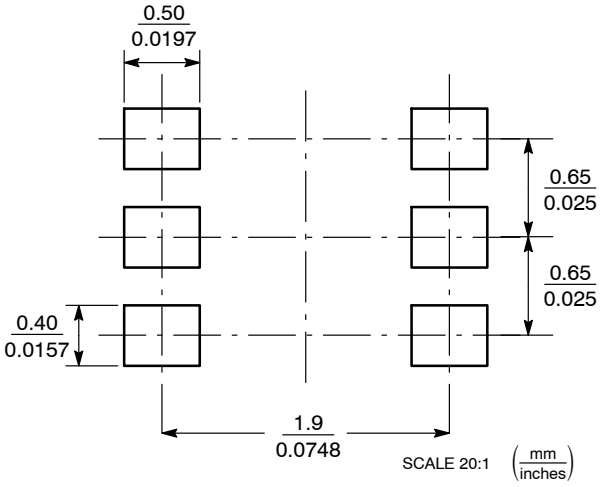




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B−01 OBSOLETE, NEW STANDARD 419B−02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3		0.20 REF			0.008 REF	
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e		0.65 BSC			0.026 BSC	
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	2.00	2.10	2.20	0.078	0.082	0.086

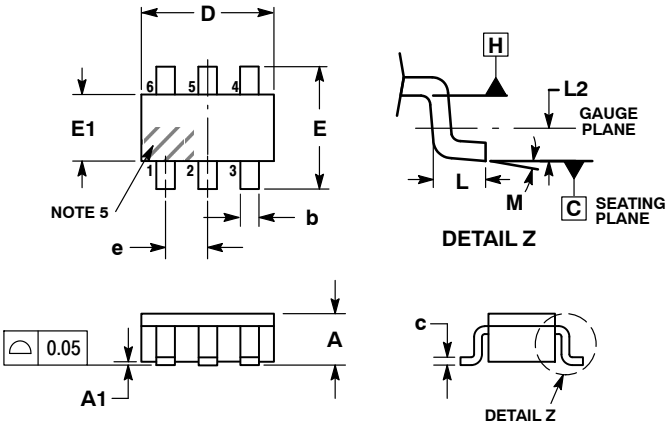
SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

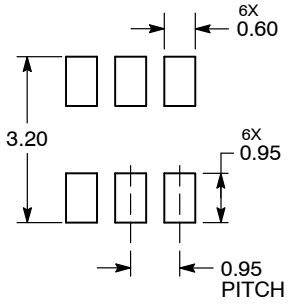
TSOP−6
CASE 318G−02
ISSUE U



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	–	10°

RECOMMENDED SOLDERING FOOTPRINT*

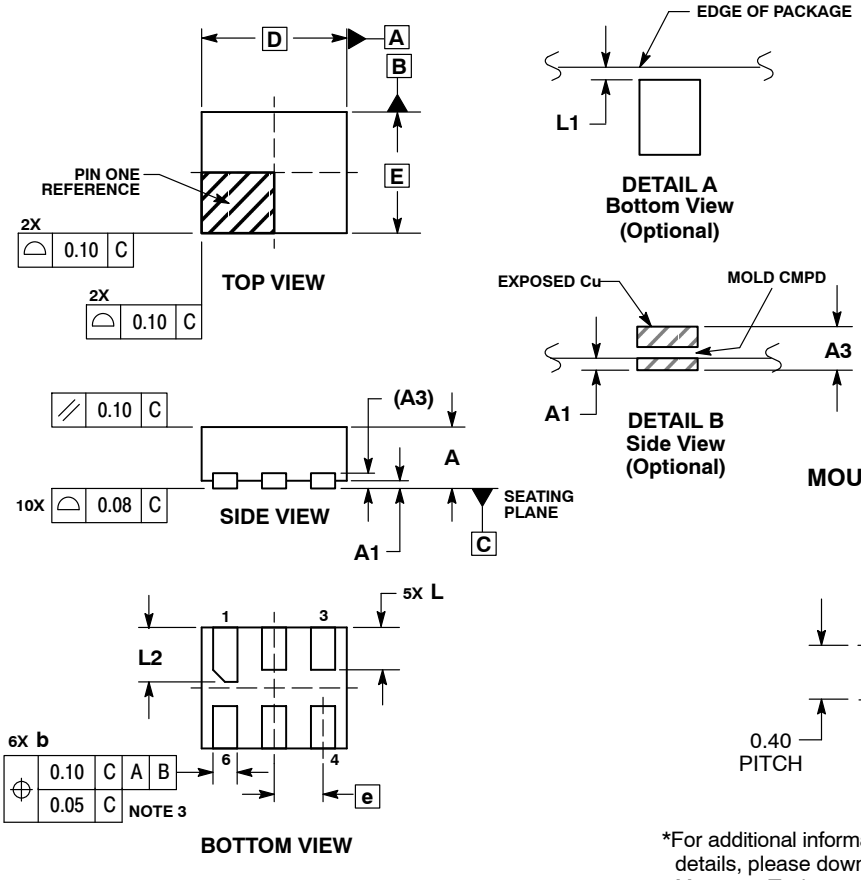


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

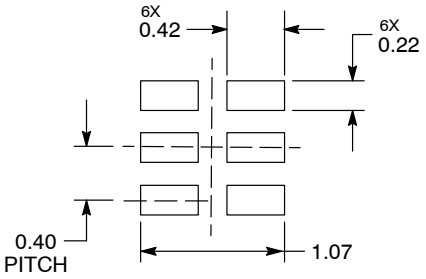
UDFN6 1.2x1.0, 0.4P
CASE 517AA−01
ISSUE C



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50

MOUNTING FOOTPRINT*

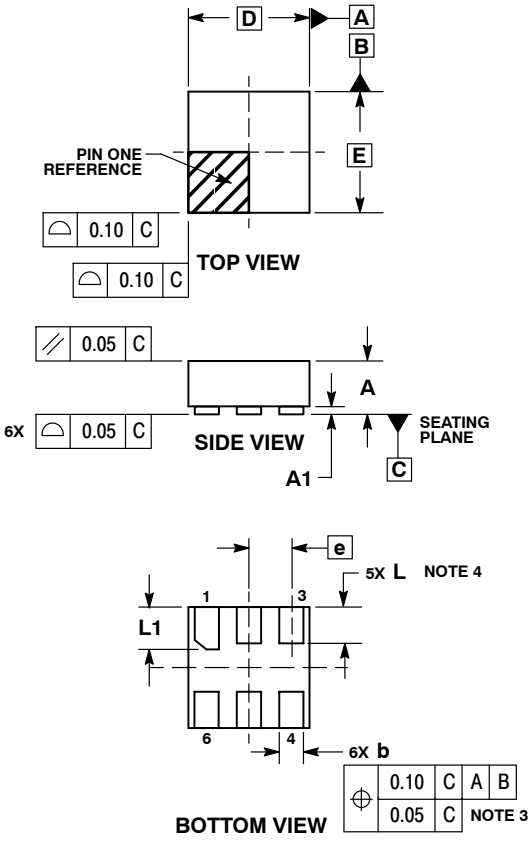


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

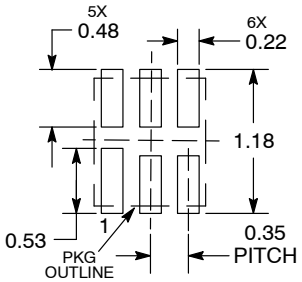
ULLGA6 1.0x1.0, 0.35P
CASE 613AD−01
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS	
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT
SOLDERMASK DEFINED*

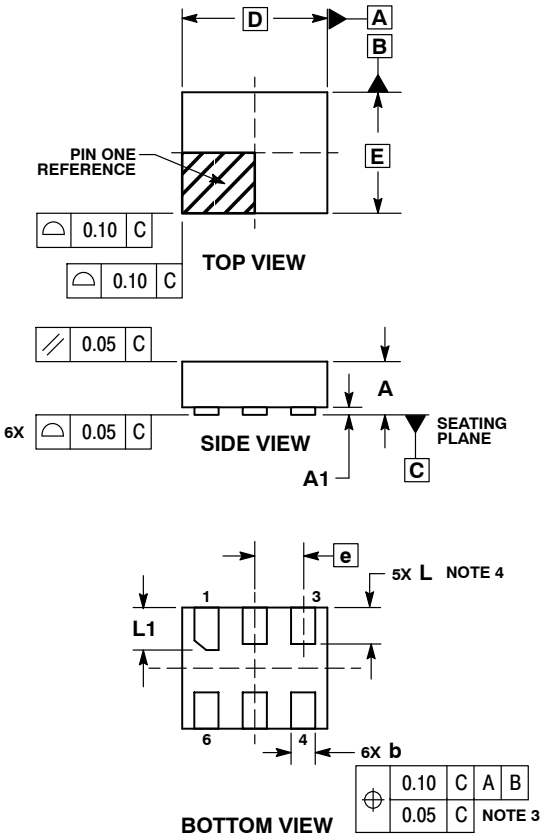


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

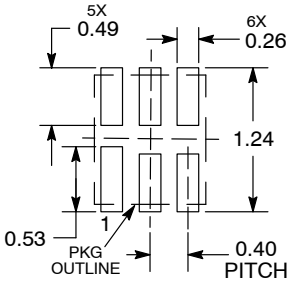
ULLGA6 1.2x1.0, 0.4P
CASE 613AE−01
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS	
DIM	MIN	MAX
A	----	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

MOUNTING FOOTPRINT
SOLDERMASK DEFINED*

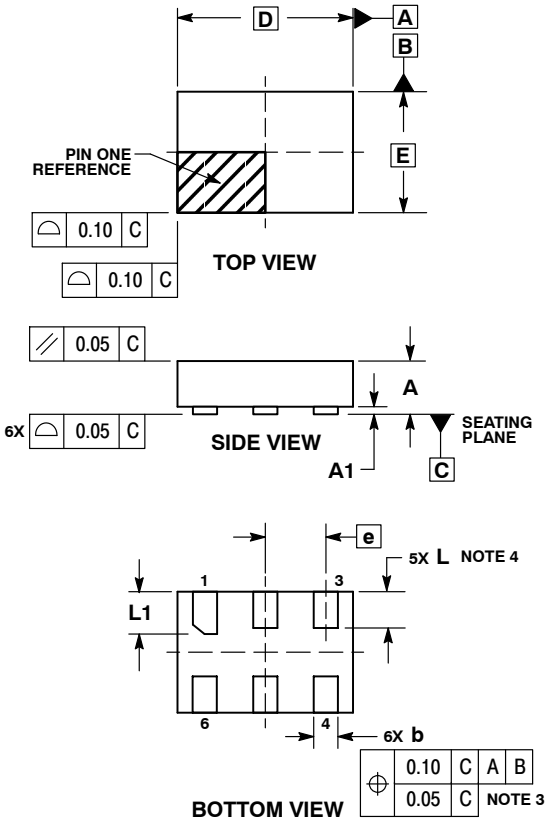


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

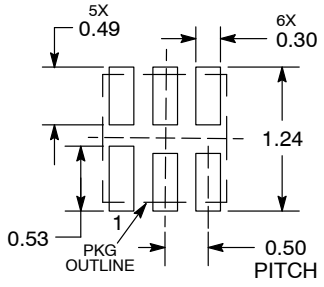
ULLGA6 1.45x1.0, 0.5P
CASE 613AF−01
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS	
DIM	MIN	MAX
A	−−−	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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